

74AXP1G17

Low-power Schmitt trigger

Rev. 1 — 6 September 2014

Product data sheet

1. General description

The 74AXP1G17 is a single Schmitt trigger buffer. It can transform slowly changing input signals into sharply defined, jitter-free output signals.

This device ensures very low static and dynamic power consumption across the entire V_{CC} range from 0.7 V to 2.75 V. It is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the potentially damaging backflow current through the device when it is powered down.

2. Features and benefits

- Wide supply voltage range from 0.7 V to 2.75 V
- Low input capacitance; $C_I = 0.5$ pF (typical)
- Low output capacitance; $C_O = 1.0$ pF (typical)
- Low dynamic power consumption; $C_{PD} = 2.5$ pF at $V_{CC} = 1.2$ V (typical)
- Low static power consumption; $I_{CC} = 0.6$ μ A (85 °C maximum)
- High noise immunity
- Complies with JEDEC standard:
 - ◆ JESD8-12A.01 (1.1 V to 1.3 V)
 - ◆ JESD8-11A.01 (1.4 V to 1.6 V)
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A.01 (2.3 V to 2.7 V)
- ESD protection:
 - ◆ HBM ANSI/ESDA/JEDEC JS-001 Class 2 exceeds 2 kV
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 2.75 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from -40 °C to +85 °C



3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74AXP1G17GM	-40 °C to +85 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74AXP1G17GN	-40 °C to +85 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74AXP1G17GS	-40 °C to +85 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202
74AXP1G17GX	-40 °C to +85 °C	X2SON5	X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 × 0.8 × 0.35 mm	SOT1226

4. Marking

Table 2. Marking

Type number	Marking code ^[1]
74AXP1G17GM	rJ
74AXP1G17GN	rJ
74AXP1G17GS	rJ
74AXP1G17GX	rJ

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

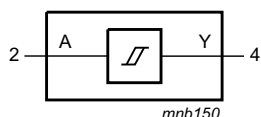


Fig 1. Logic symbol

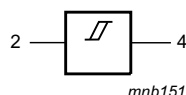


Fig 2. IEC logic symbol

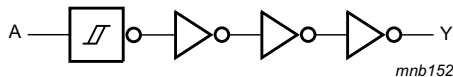
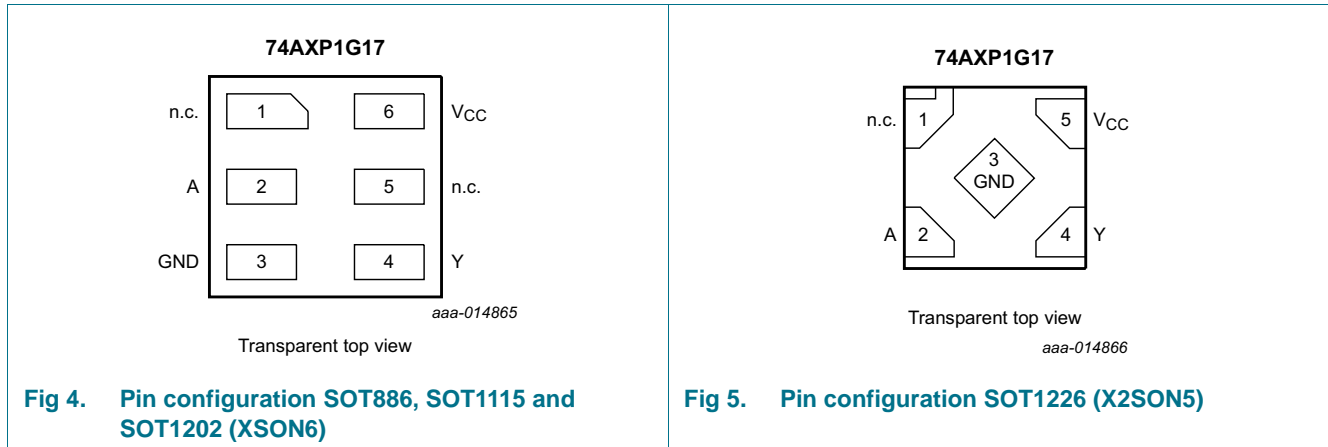


Fig 3. Logic diagram

6. Pinning information

6.1 Pinning



6.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	X2SON5	XSON6	
n.c.	1	1	not connected
A	2	2	data input
GND	3	3	ground (0 V)
Y	4	4	data output
n.c.	-	5	not connected
V _{CC}	5	6	supply voltage

7. Functional description

Table 4. Function table^[1]

Input	Output
A	Y
L	L
H	H

[1] H = HIGH voltage level; L = LOW voltage level.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+3.3	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
V_I	input voltage		[1] -0.5	+3.3	V
I_{OK}	output clamping current	$V_O < 0$ V	-50	-	mA
V_O	output voltage		[1] -0.5	+3.3	V
I_O	output current	$V_O = 0$ V to V_{CC}	-	± 20	mA
I_{CC}	supply current		-	50	mA
I_{GND}	ground current		-50	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +85 °C	-	250	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		0.7	2.75	V
V_I	input voltage		0	2.75	V
V_O	output voltage	Active mode	0	V_{CC}	V
		Power-down mode; $V_{CC} = 0$ V	0	2.75	V
T_{amb}	ambient temperature		-40	+85	°C

10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions, unless otherwise specified; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	$T_{amb} = -40\text{ °C to }+85\text{ °C}$				Unit	
			Min	Typ 25 °C	Max 25 °C	Max 85 °C		
V_{T+}	positive-going threshold voltage	see Figure 6 and Figure 7						
		$V_{CC} = 0.75\text{ V to }0.85\text{ V}$	$0.3V_{CC}$	-	$0.8V_{CC}$	$0.8V_{CC}$	V	
		$V_{CC} = 1.1\text{ V to }1.95\text{ V}$	$0.4V_{CC}$	-	$0.7V_{CC}$	$0.7V_{CC}$	V	
V_{T-}	negative-going threshold voltage	see Figure 6 and Figure 7						
		$V_{CC} = 0.75\text{ V to }0.85\text{ V}$	$0.2V_{CC}$	-	$0.7V_{CC}$	$0.7V_{CC}$	V	
		$V_{CC} = 1.1\text{ V to }1.95\text{ V}$	$0.3V_{CC}$	-	$0.6V_{CC}$	$0.6V_{CC}$	V	
V_H	hysteresis voltage	see Figure 6 and Figure 7						
		$V_{CC} = 0.75\text{ V to }0.85\text{ V}$	$0.06V_{CC}$	-	$0.5V_{CC}$	$0.5V_{CC}$	V	
		$V_{CC} = 1.1\text{ V to }1.95\text{ V}$	$0.1V_{CC}$	-	$0.4V_{CC}$	$0.4V_{CC}$	V	
V_{OH}	HIGH-level output voltage	$I_O = -20\text{ }\mu\text{A}; V_{CC} = 0.7\text{ V}$	-	0.69	-	-	V	
		$I_O = -100\text{ }\mu\text{A}; V_{CC} = 0.75\text{ V}$	0.65	-	-	-	V	
		$I_O = -2\text{ mA}; V_{CC} = 1.1\text{ V}$	0.825	-	-	-	V	
		$I_O = -3\text{ mA}; V_{CC} = 1.4\text{ V}$	1.05	-	-	-	V	
		$I_O = -4.5\text{ mA}; V_{CC} = 1.65\text{ V}$	1.2	-	-	-	V	
		$I_O = -8\text{ mA}; V_{CC} = 2.3\text{ V}$	1.7	-	-	-	V	
V_{OL}	LOW-level output voltage	$I_O = 20\text{ }\mu\text{A}; V_{CC} = 0.7\text{ V}$	-	0.01	-	-	V	
		$I_O = 100\text{ }\mu\text{A}; V_{CC} = 0.75\text{ V}$	-	-	0.1	0.1	V	
		$I_O = 2\text{ mA}; V_{CC} = 1.1\text{ V}$	-	-	0.275	0.275	V	
		$I_O = 3\text{ mA}; V_{CC} = 1.4\text{ V}$	-	-	0.35	0.35	V	
		$I_O = 4.5\text{ mA}; V_{CC} = 1.65\text{ V}$	-	-	0.45	0.45	V	
		$I_O = 8\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.7	0.7	V	
I_I	input leakage current	$V_I = 0\text{ V to }2.75\text{ V}; V_{CC} = 0\text{ V to }2.75\text{ V}$	[1]	-	0.001	± 0.1	± 0.5	μA
I_{OFF}	power-off leakage current	V_I or $V_O = 0\text{ V to }2.75\text{ V}; V_{CC} = 0\text{ V}$	[1]	-	0.01	± 0.1	± 0.5	μA
ΔI_{OFF}	additional power-off leakage current	V_I or $V_O = 0\text{ V or }2.75\text{ V}; V_{CC} = 0\text{ V to }0.1\text{ V}$	[1]	-	0.02	± 0.1	± 0.5	μA
I_{CC}	supply current	$V_I = 0\text{ V or }V_{CC}; I_O = 0\text{ A}$	[1]	-	0.01	0.3	0.6	μA
ΔI_{CC}	additional supply current	$V_I = V_{CC} - 0.5\text{ V}; I_O = 0\text{ A}; V_{CC} = 2.5\text{ V}$	-	-	2	100	150	μA

[1] Typical values are measured at $V_{CC} = 1.2\text{ V}$.

10.1 Waveform transfer characteristics

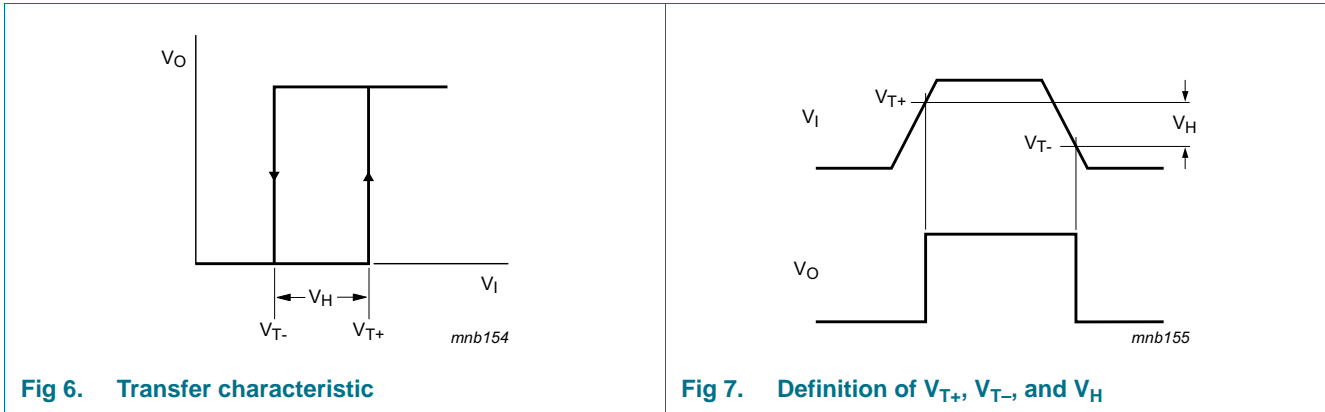


Fig 6. Transfer characteristic

Fig 7. Definition of V_{T+} , V_{T-} , and V_H

11. Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit, see Figure 14.

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = -40 °C to +85 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t _{pd}	propagation delay	A to Y; see Figure 8 ^{[2][3]}						
		V _{CC} = 0.75 V to 0.85 V	3	11	39	2	136	ns
		V _{CC} = 1.1 V to 1.3 V	2.1	4.4	7.0	1.9	7.3	ns
		V _{CC} = 1.4 V to 1.6 V	1.8	3.3	4.7	1.6	5.0	ns
		V _{CC} = 1.65 V to 1.95 V	1.5	2.8	3.9	1.3	4.2	ns
		V _{CC} = 2.3 V to 2.7 V	1.2	2.3	3.0	1.1	3.3	ns
t _t	transition time	V _{CC} = 2.7 V; see Figure 8 ^[4]	-	-	-	1.0	-	ns
C _I	input capacitance	V _I = 0 V or V _{CC} ; V _{CC} = 0 V to 2.75 V	-	0.5	-	-	-	pF
C _O	output capacitance	V _O = 0 V; V _{CC} = 0 V	-	1.0	-	-	-	pF

Table 8. Dynamic characteristics ...continued
 Voltages are referenced to GND (ground = 0 V); for test circuit, see [Figure 14](#).

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = -40 °C to +85 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
C _{PD}	power dissipation capacitance	f _i = 1 MHz; V _I = 0 V to V _{CC}	[5]					
		V _{CC} = 0.75 V to 0.85 V		-	2.3	-	-	pF
		V _{CC} = 1.1 V to 1.3 V		-	2.5	-	-	pF
		V _{CC} = 1.4 V to 1.6 V		-	2.6	-	-	pF
		V _{CC} = 1.65 V to 1.95 V		-	2.7	-	-	pF
		V _{CC} = 2.3 V to 2.7 V		-	3.1	-	-	pF

- [1] All typical values are measured at nominal V_{CC}.
- [2] t_{pd} is the same as t_{PLH} and t_{PHL}.
- [3] For additional propagation delay values at different load capacitances, see [Figure 9](#) to [Figure 13](#).
- [4] t_t is the same as t_{THL} and t_{TLH}.
- [5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + C_L \times V_{CC}^2 \times f_o$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in V;

12. Waveforms

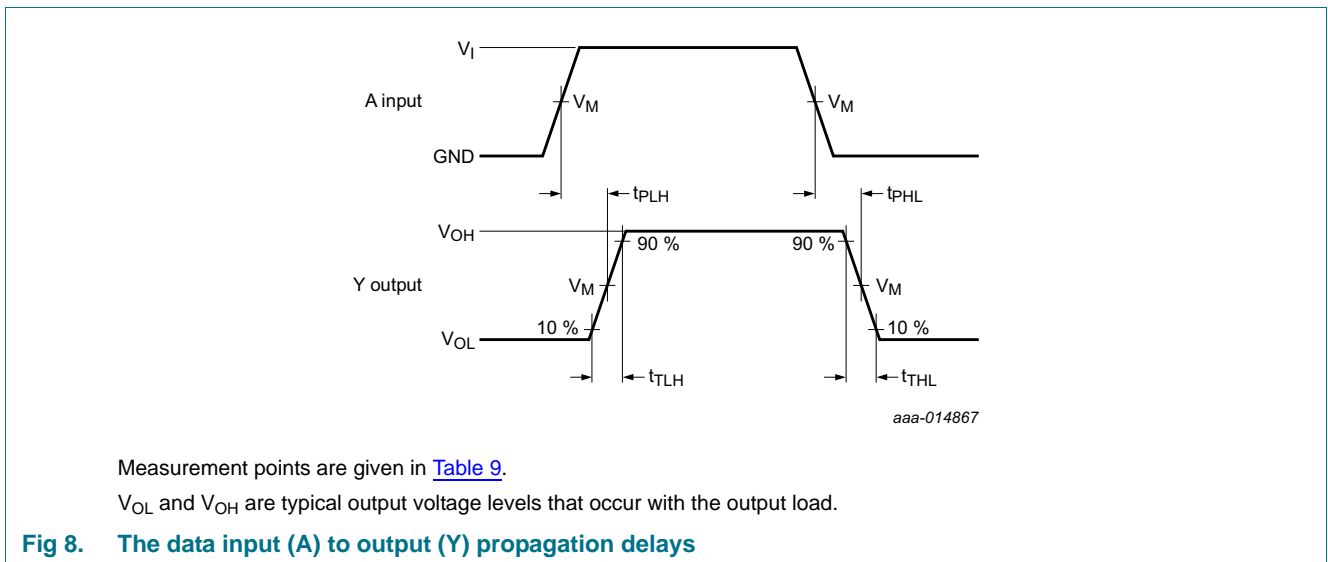
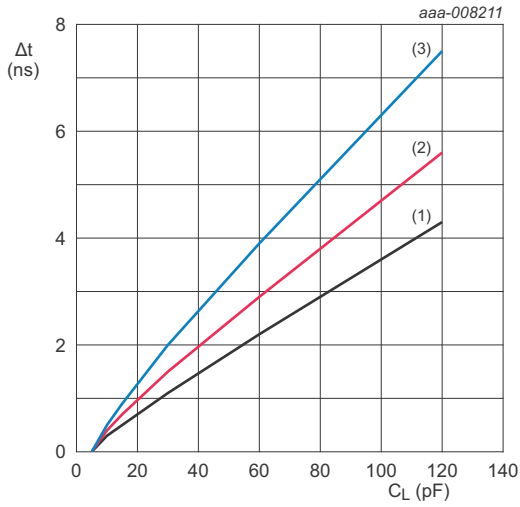


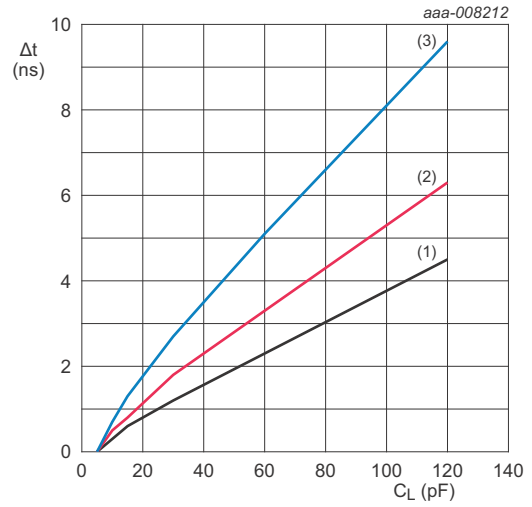
Table 9. Measurement points

Supply voltage	Input			Output
V _{CC}	V _M	V _I	t _r = t _f	V _M
0.75 V to 2.7 V	0.5V _{CC}	V _{CC}	≤ 3.0 ns	0.5V _{CC}



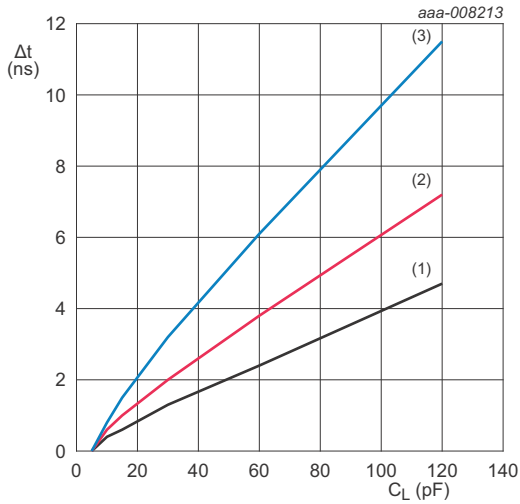
- $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ unless otherwise specified.
- (1) Minimum: $V_{CC} = 2.7\text{ V}$
 - (2) Typical: $T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CC} = 2.5\text{ V}$
 - (3) Maximum: $V_{CC} = 2.3\text{ V}$

Fig 9. Additional t_{pd} versus load capacitance



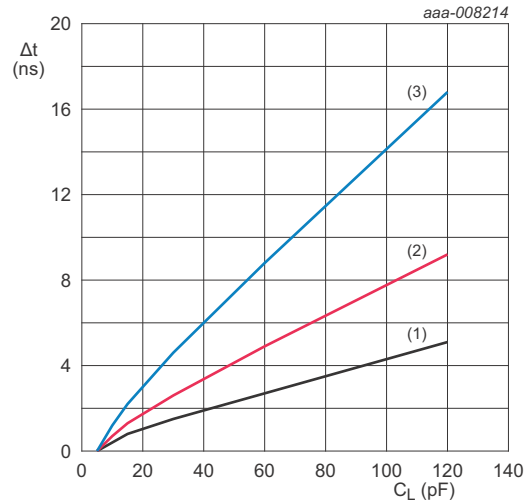
- $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ unless otherwise specified.
- (1) Minimum: $V_{CC} = 1.95\text{ V}$
 - (2) Typical: $T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CC} = 1.8\text{ V}$
 - (3) Maximum: $V_{CC} = 1.65\text{ V}$

Fig 10. Additional t_{pd} versus load capacitance



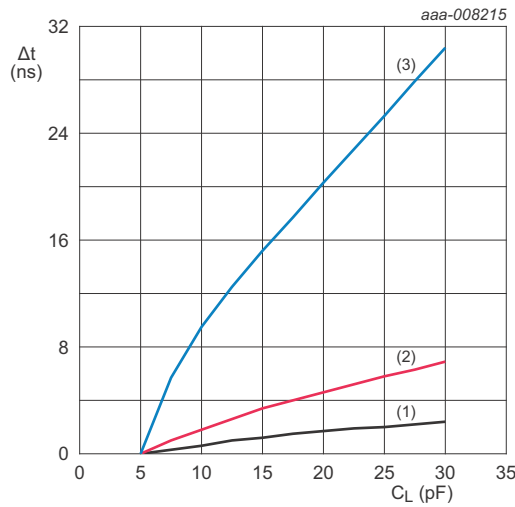
- $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ unless otherwise specified.
- (1) Minimum: $V_{CC} = 1.6\text{ V}$
 - (2) Typical: $T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CC} = 1.5\text{ V}$
 - (3) Maximum: $V_{CC} = 1.4\text{ V}$

Fig 11. Additional t_{pd} versus load capacitance



- $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ unless otherwise specified.
- (1) Minimum: $V_{CC} = 1.3\text{ V}$
 - (2) Typical: $T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{CC} = 1.2\text{ V}$
 - (3) Maximum: $V_{CC} = 1.1\text{ V}$

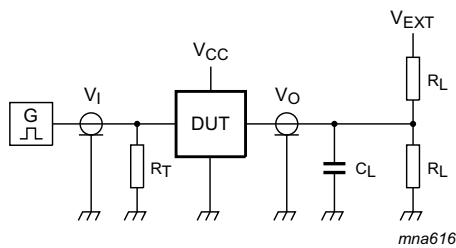
Fig 12. Additional t_{pd} versus load capacitance



T_{amb} = -40 °C to +85 °C unless otherwise specified.

- (1) Minimum: V_{CC} = 0.85 V
- (2) Typical: T_{amb} = 25 °C; V_{CC} = 0.8 V
- (3) Maximum: V_{CC} = 0.75 V

Fig 13. Additional t_{pd} versus load capacitance



Test data is given in [Table 10](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 14. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Load		V _{EXT}		
V _{CC}	C _L	R _L	t _{PLH} , t _{PHL}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ}
0.75 V to 2.7 V	5 pF	10 kΩ	0 V	0 V	2V _{CC}

13. Package outline

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

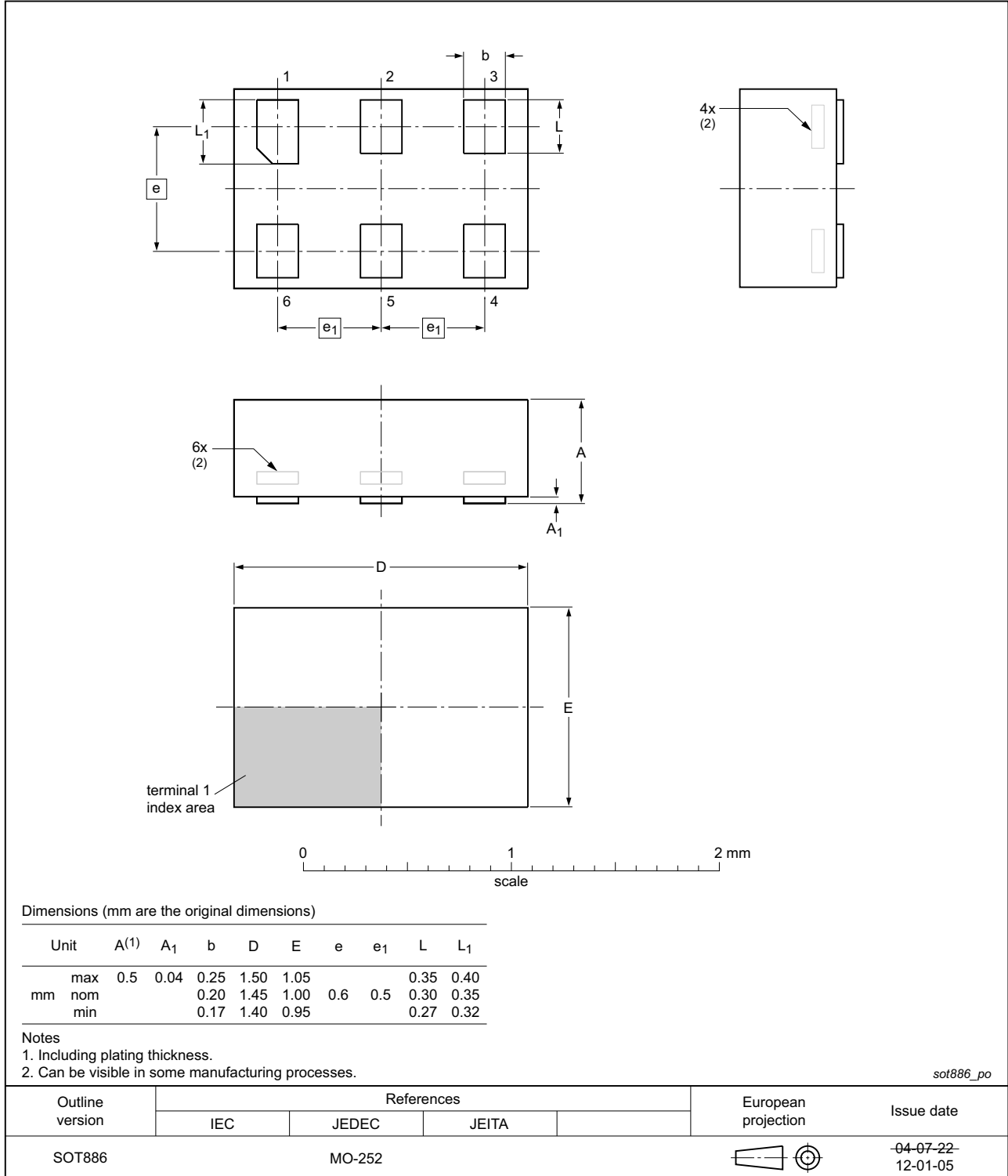


Fig 15. Package outline SOT886 (XSON6)

**XSON6: extremely thin small outline package; no leads;
6 terminals; body 0.9 x 1.0 x 0.35 mm**

SOT1115



Fig 16. Package outline SOT1115 (XSON6)

**XSON6: extremely thin small outline package; no leads;
6 terminals; body 1.0 x 1.0 x 0.35 mm**

SOT1202

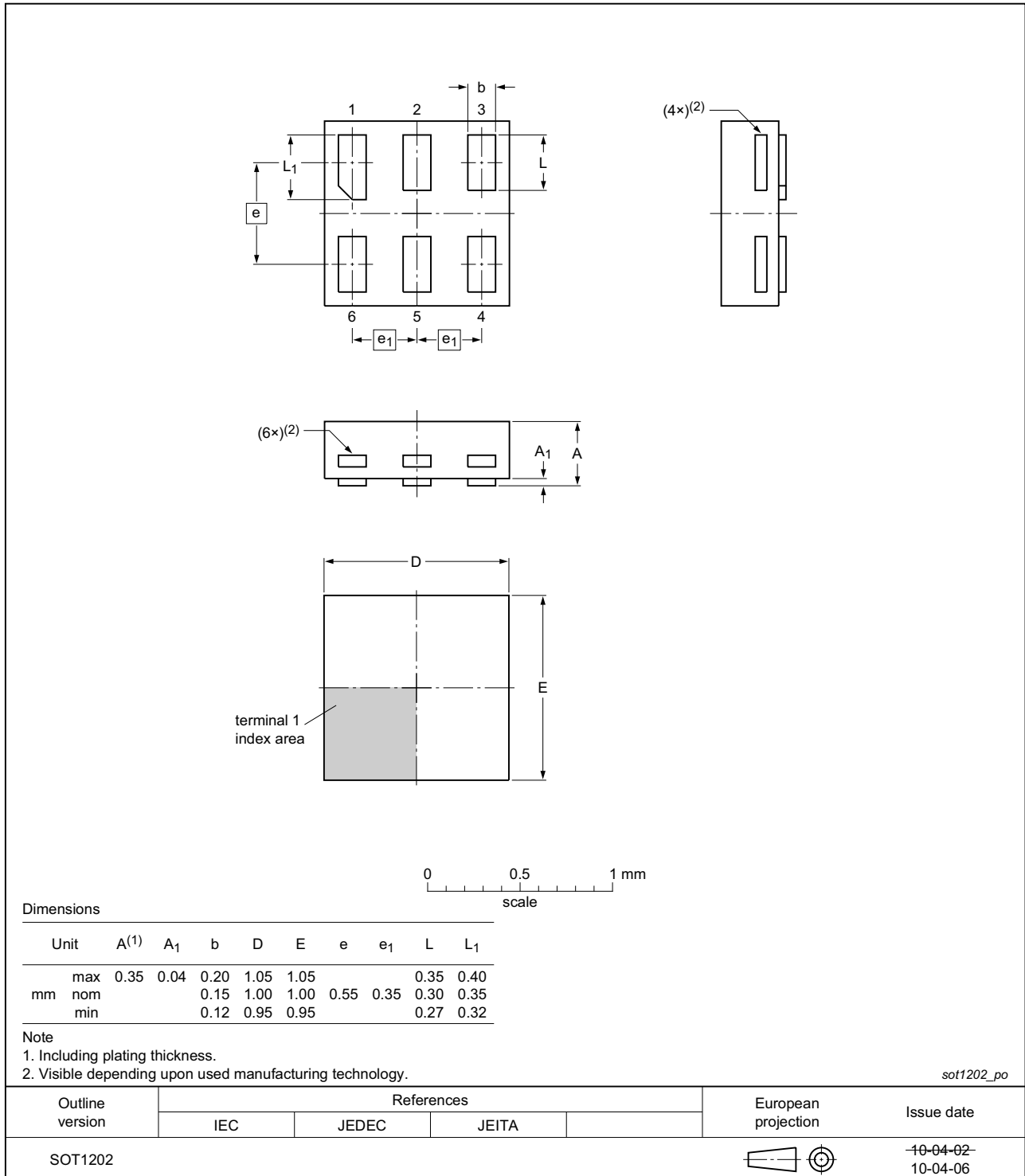


Fig 17. Package outline SOT1202 (XSON6)

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads;
5 terminals; body 0.8 x 0.8 x 0.35 mm

SOT1226

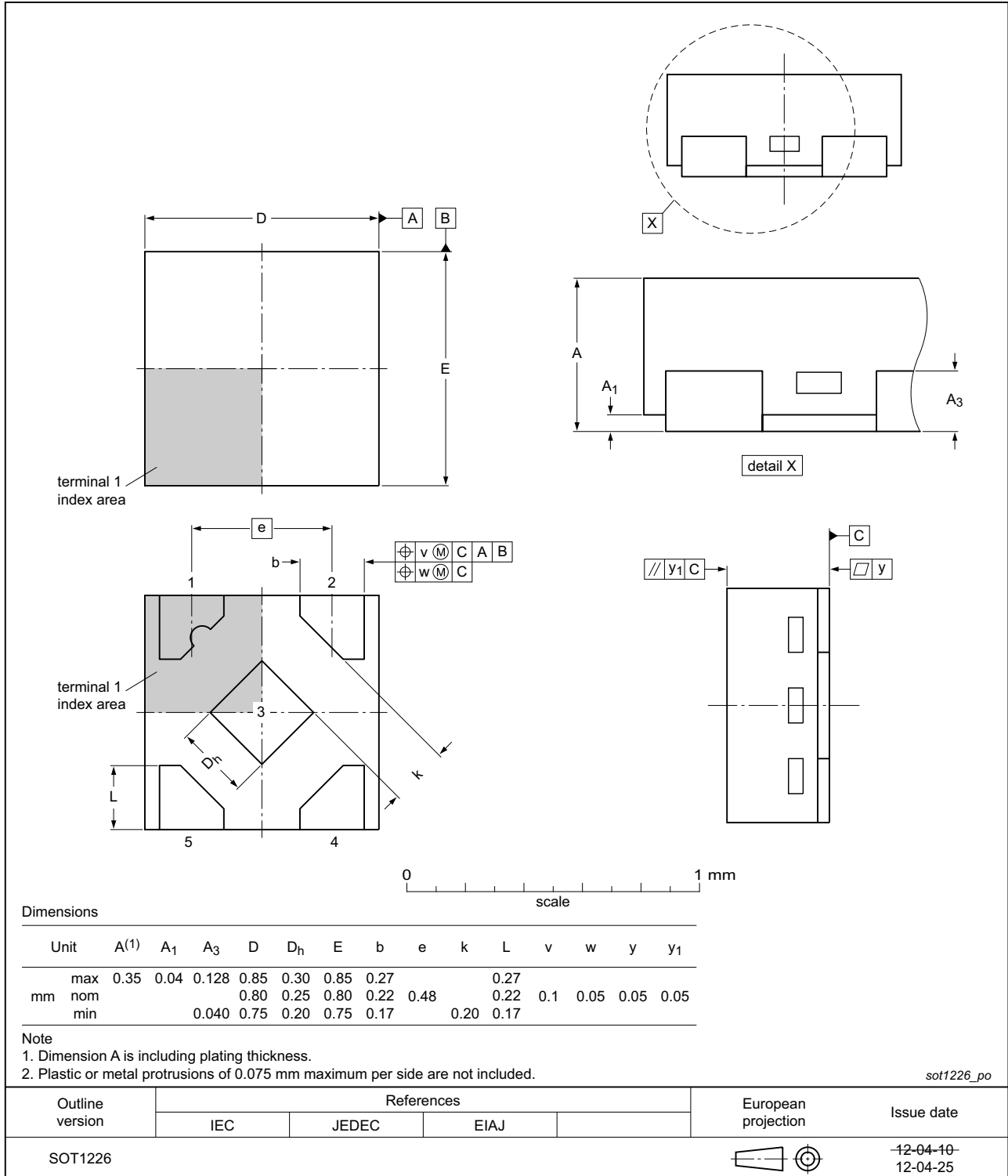


Fig 18. Package outline SOT1226 (X2SON5)

14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model

15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AXP1G17 v.1	20141006	Product data sheet	-	-

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

16.4 Trademarks

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17. Contact information

For more information, please visit: <http://www.nxp.com>

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